LNJ314G83RA

Hight Bright Surface Mounting Chip LED

USS Type

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	40	mW	
Forward current	I_{F}	15	mA	
Pulse forward current *	I_{FP}	50	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

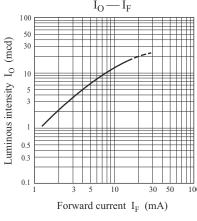
■ Lighting Color

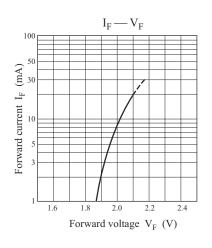
• Yellow Green

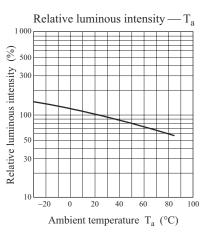
■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

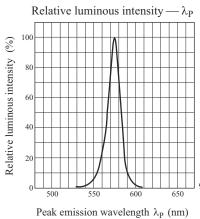
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *	I _O	$I_F = 10 \text{ mA}$	6.4	12		mcd
Reverse current	I_R	$V_R = 4 V$			100	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$		2.03	2.50	V
Peak emission wavelength	λ_{P}	$I_F = 10 \text{ mA}$		575		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		15		nm

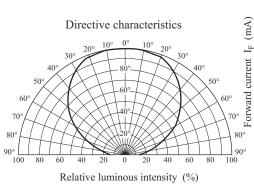
Note) *: Measurement tolerance: ±20%

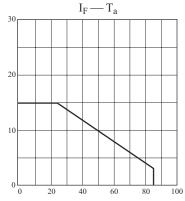








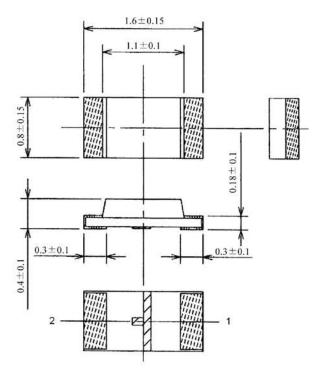




Ambient temperature Ta (°C)

■ Package (Unit: mm)

KLTFTN2K1400



- Pin name
 - 1: Anode
 - 2: Cathode

2 SHD00646BEK

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